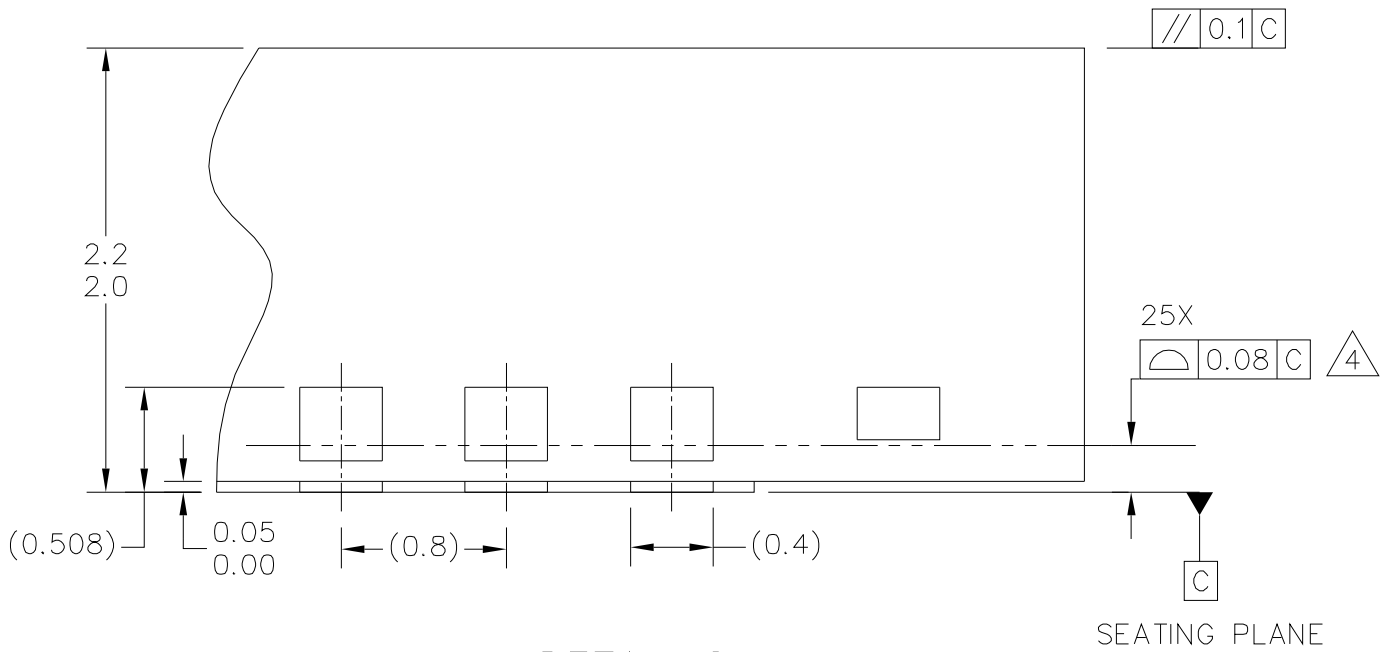



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TITLE: PQFN (SAW), THERMALLY ENHANCED 8 X 8 X 2.1, 0.8 PITCH, 24 TERMINAL		DOCUMENT NO: 98ASA10760D	REV: A
		CASE NUMBER: 1894-02	29 MAY 2012
		STANDARD: NON-JEDEC	



DETAIL G  
VIEW ROTATED 90° CW

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	CASE NUMBER: 1894-02	29 MAY 2012	
	STANDARD: NON-JEDEC		

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.

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